



Biomaterials and Biofabrication

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Message from the Guest Editors

Dear Colleagues,

Biomaterials have grown to be one of the most important academy and industry fields that can strongly contribute to major advances in human health. More recently, biomaterials that can be used as enabling medical platforms in combination with biofabrication technologies have emerged as a powerful paradigm for the next generation of medicine.

In this Special Issue, we are inviting submissions exploring the latest advances in basic and application research in the field of biomaterials and biofabrication (e.g., cell and tissue engineering scaffolds, wearable medical sensors, micro- and nanomedicine, 3D bioprinting, biologically inspired engineering, organ chips, bioelectronics, etc.). Communications and reviews are also welcomed.

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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